AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) An input device comprising:

an electrostatic-capacitance-type input sensor including a flexible substrate;

a plurality of X electrodes that are formed on one surface of the flexible substrate and that are disposed on an insulating layer and a plurality of Y electrodes that are disposed on the insulating layer; and

an extension section that is extended from the flexible substrate; and lead wiring of the X electrodes and the Y electrodes bundled in the extension section and connected to thea non-flexible circuit substrate, wherein the Y electrodes are connected to the lead wiring via a through-hole part provided on the insulating layer,

wherein a protrusion dimension of a portion of the insulating layer which overlaps
the extension section is shorter than a protrusion dimension of the extension section
such that the insulating layer does not overlap an end portion of the lead wiring of the X
and Y electrodes bundled in the extension section, and

wherein the X and Y electrodes are connected to athe non-flexible circuit substrate provided on one surface of the extension section, and the other surface of the flexible substrate of the electrostatic-capacitance-type input sensor is bonded to the reverse surface of a curved portion of a support plate, and the other surface of the flexible substrate of the extension section is bonded to a flattened portion continuously disposed from the curved portion so that an input operation is conducted by performing

a contact operation along the obverse surface of the curve portion without viewing the electrostatic-capacitance type input sensor and the circuit substrate from an outer surface.

- 2. (Original) An electrostatic-capacitance-type coordinate input device according to Claim 1, wherein a recess to which the input sensor is fitted is formed on the rear surface of said support plate at a position where said input sensor is bonded.
- 3. (Currently Amended) An electrostatic-capacitance-type coordinate input device according to Claim 1, wherein a pointing section for pointing a position of said input sensor is formed of a recessed portion or a projecting portion, a color display, or changes in surface roughness matching the shape of the input sensor.

4. – 7. (Canceled)

8. (Currently Amended) A device, comprising;

an input device having a coordinate-input sensor formed on a flexible substrate and having an electrode layer that includes a plurality of X electrodes and Y electrodes formed on one surface of the flexible substrate for detecting electrostatic capacitance, the X electrodes and Y electrodes having lead wiring;

a device housing having an insulating portion layer having obverse and reverse sides, the obverse side being exposed;

wherein the input sensor is disposed on the reverse side of the insulating portionlayer and an input operation is performable at the obverse side,

wherein the coordinate-input sensor has an extension section, a non-flexible circuit substrate to which the electrodes are connected, the non-flexible circuit substrate being disposed on one surface of he extension section, the other surface of the flexible substrate of the input sensor being bonded to the reverse surface of a curved portion of a support plate, and the other surface of the flexible substrate of the extension section being bonded to a flattened portion of a support plate continuously disposed from the curved portion, so that an input operation is conducted by performing a contact operation along the obverse surface of the curve portion without viewing the electrostatic-capacitance type input sensor and the circuit substrate from an outer surface.

wherein the lead wiring of the X electrodes and the Y electrodes is bundled in the extension section and connected to the non-flexible circuit substrate, wherein the Y electrodes are connected to the lead wiring via a through-hole part provided on the insulating layer and

wherein a protrusion dimension of a portion of the insulating layer which overlaps
the extension section is shorter than a protrusion dimension of the extension section
such that the insulating layer does not overlap an end portion of the lead wiring of the X
and Y electrodes bundled in the extension section.

9. (Previously Presented) The device according to claim 8, wherein the input sensor is bonded to an arcuate section formed in the insulating portion.

- 10. (Previously Presented) The device according to claim 8, wherein the input sensor is bonded to a recessed area formed in the reverse side.
- 11. (Previously Presented) An electrostatic-capacitance-type coordinate input device according to Claim 1, wherein the reverse surface of the flexible substrate corresponding to the extension section is bonded to a rear surface of a planar portion of the insulating support plate.
- 12. (Previously Presented) The device according to claim 8, wherein the reverse surface of the flexible substrate corresponding to the extension section is bonded to a rear surface of a planar portion of the insulating support plate